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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re: Patent Application of

Mark Pavier

Date: January 22, 2001

Serial No. 09/718,932

Group Art Unit:

Filed: November 22, 2000

Examiner:

For: **POWER SEMICONDUCTOR DIE ATTACH PROCESS USING
CONDUCTIVE ADHESIVE FILM**

Asst. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

REQUEST FOR APPROVAL OF DRAWING CORRECTIONS

Sir:

You are advised that, subject to the approval of the Patent Examiner, applicant proposes to amend drawing Fig. 5 as indicated in red on the enclosed photocopy.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on January 22, 2001

Respectfully submitted,

Samuel H. Weiner

Name of applicant, assignee or
Registered Representative

Signature

January 22, 2001

Date of Signature

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